

a leadframe base made of copper or copper alloy;  
a first layer of nickel deposited on said copper or copper alloy;  
a layer of an alloy of nickel and palladium on said first nickel layer;  
a second layer of nickel on said alloy layer, said second nickel layer deposited to be suitable for bending of said lead segments, wire bonding, and solder attachment;  
a layer of palladium, said palladium layer deposited to be suitable for protecting the nickel surface for wire bonding and solderability, and for adhesion to molding compound; and  
a layer of gold selectively covering [outer areas] portions of said lead segments external to said package, intended for solder attachment.

Claim 11. (Amended) A packaged semiconductor device comprising:

a leadframe comprising a chip mount pad for an integrated circuit chip and a plurality of lead segments having their first end near said mount pad and their second end remote from said mount pad;  
said leadframe having a first surface layer of nickel, a layer of an alloy of nickel and palladium, a second layer of nickel, and a layer of palladium;  
said leadframe further having an outermost layer of gold selectively covering portions of said second ends of said lead segments external to said package, in a thickness suitable to optimize solder attachment;  
an integrated circuit chip attached to said mount pad; and  
bonding wires interconnecting said chip and said first ends of said lead segments. [encapsulation material surrounding said chip, bonding wires and said first ends of said lead